

CLAIMS

1. A method for forming a multilayer circuit structure, which comprises steps of forming a curable composition film  
5 that contains an insulating polymer and a curing agent, as the outermost layer of an inner layer board, then bringing a compound that has a structure capable of coordinating to a metal, into contact with the surface of the curable composition film, then curing the curable composition film to form an electrical  
10 insulating layer, then hydrophilicating the surface of the resulting electrical insulating layer, then forming a metal thin-film layer of an ethylenediaminetetraacetate-copper complex on the surface of the electrical insulating layer, and then forming a conductor circuit layer that contains the metal  
15 thin-film layer.

2. The method for forming a multilayer circuit structure as claimed in claim 1, wherein the hydrophilicating treatment step is a step of bringing the electrical insulating layer into contact with a mixture solution that comprises from 65 g/liter  
20 to 150 g/liter of potassium permanganate and from 0.75 normalities to 1.5 normalities of an alkali hydroxide, for surface-treatment of the electrical insulating layer.

3. The method for forming a multilayer circuit structure as claimed in claim 1, wherein the curable composition film  
25 that contains an insulating polymer and a curing agent and is

formed as the outermost layer of the inner layer board is formed according to any of a method of laminating any of a shaped film or sheet of a curable composition that contains an insulating polymer and a curing agent, on the inner layer board, or a method 5 of by applying a varnish prepared by dissolving a curable composition containing an insulating polymer and a curing agent in a solvent, onto the surface of the inner layer board and drying it thereon.

4. The method for forming a multilayer circuit structure 10 as claimed in claim 1, which includes a step of heating the inner layer board with the conductor circuit layer formed thereon, after the step of forming the conductor circuit layer.

5. A substrate having a multilayer circuit structure, in which the multilayer circuit structure is manufactured 15 according to the multilayer circuit structure-forming method of claim 1.